

# The 4th IEEE International Conference on Electrical Materials and Power Equipment

## CALL FOR PAPERS

May 7<sup>th</sup>-10<sup>th</sup>, 2023, Shanghai, China

### IMPORTANT DATES

|                              |               |
|------------------------------|---------------|
| One Page Abstract Submission | Dec. 20, 2022 |
| Author Notification:         | Jan. 20, 2023 |
| Manuscript Submission:       | Feb. 20, 2023 |
| Acceptance of Manuscript:    | Mar. 28, 2023 |



# ICEMPE 2023



## GENERAL INFORMATION

It's our great pleasure to invite you to join us for the 4th IEEE International Conference on Electrical Materials and Power Equipment (ICEMPE 2023), which will provide a forum within the international academic and engineering community in the field of electrical materials and power equipment.

ICEMPE 2023 will be held in Shanghai, China on May 7th-10th, 2023. It is co-sponsored by the Engineering Dielectrics Committee of China Electrotechnical Society (CES) and the IEEE Dielectrics and Electrical Insulation Society (DEIS), and it will be organized and technically supported by Shanghai Jiao Tong University. ICEMPE is an extension of National Conference on Engineering Dielectrics (NCED) in China, which was founded in 1983 as a biennial forum. The 1<sup>st</sup>, 2<sup>nd</sup> and 3<sup>rd</sup> ICEMPE has been successfully held in Xi'an in 2017, Guangzhou in 2019, and Chongqing in 2021, respectively.

We are looking forward to your participation!

ORGANIZED BY



SHANGHAI JIAO TONG  
UNIVERSITY

## TOPICS

1. Dielectric phenomenon: conduction, polarization, breakdown, and space charge.
2. Performance, composition, and structure of insulating materials: including nanocomposite, ecofriendly dielectrics, and biodielectrics.
3. Fabrication, detection, operation, assessment, and digitalization of power equipment: including cable, motor, transformer, GIS, HVDC, power module, etc.
4. Electrical insulation techniques under extreme conditions: high temperature, high pressure, high vacuum, electrical insulation in space.
5. Energy storage and superconducting materials and technologies: including superconducting material, battery, electrode material, condition monitoring, and life evaluation of energy storage and superconducting material and equipment.
6. Others: including treeing, aging, life assessment, modeling and simulations, measurement techniques, etc.

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## PAPER SUBMISSION

The authors are invited to submit an electronic version of the papers via the conference website: <http://www.icempe.org>. The official language of the conference is English. Instructions and detailed information on the conference will be posted on the conference website. All accepted papers will be published in IEEE Xplore (indexed by EI).

## REGISTRATION

### Early Bird (Before Apr. 7, 2023)

|                            |                     |
|----------------------------|---------------------|
| IEEE Student Member        | 400 USD or 2850 RMB |
| Student Member             | 500 USD or 3565 RMB |
| IEEE/CES/IEEEJ/KIEE Member | 600 USD or 4280 RMB |
| Others                     | 650 USD or 4650 RMB |

### Normal (After Apr. 7, 2023)

|                            |                     |
|----------------------------|---------------------|
| IEEE Student Member        | 450 USD or 3200 RMB |
| Student Member             | 550 USD or 3950 RMB |
| IEEE/CES/IEEEJ/KIEE Member | 650 USD or 4650 RMB |
| Others                     | 700 USD or 5000 RMB |

### Virtual (Before May. 1, 2023)

|                                |                     |
|--------------------------------|---------------------|
| Only international participant | 200 USD or 1450 RMB |
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## CONTACT US

Secretary: Jiandong Wu

Tel: +86 13601879534

Email: [icempe@sjtu.edu.cn](mailto:icempe@sjtu.edu.cn)

Web: <http://www.icempe.org>

